



MEMS/NEMS North America TC Chapter

NA Standards Fall Meetings 2019

Monday, November 4

SEMI Headquarters, Milpitas, California

10:00–12:00 Noon

AGENDA

1 Welcome/Call to Order

- 1.1 Introductions
- 1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)
- 1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Staff Report

4 Ballot Review

- 4.1 Document 6018 — New Standard: Specification for Silicon Substrates used in fabrication of MEMS Devices

5 Subcommittee & Task Force Reports

- 5.1 Joint MSIG, MEMS Substrate Task Force & MEMS Material Characterization Task Force
- 5.2 MEMS Microfluidics Task Force – *no meeting*

6 Old Business

- 6.1 Current SNARFs to addressed
 - 6.1.1 Document 6007, New Standard: Guide for Use of Test Patterns for Characterizing a Deep Reactive Ion Etching (DRIE) Process

7 New Business

- 7.1 SEMI | MSIG Working Groups
 - 7.1.1 Manufacturing WG: Discuss new focus options
 - 7.1.2 Device WG: Environment/Gas Sensors next steps
- 7.2 MIPI Alliance
- 7.3 LoRa Alliance
- 7.4 Standards at SEMI
- 7.5 MEMS needed in Europe, Asia, China?
- 7.6 Other identified challenges to work on

8 Action Item Review

- 8.1 Open Action Items (*None*)
- 8.2 New Action Items

9 Next Meeting and Adjournment

- 9.1 The next meeting is scheduled for Monday, March 30, in conjunction with the NA Standards Spring 2020 Meetings at SEMI Headquarters in Milpitas, California.

Tentative Schedule:

- Monday, March 30
 - TBD Microfluidics (TF)
 - TBD Joint MSIG, MEMS Substrate, and Material Characterization (TFs)
 - TBD MEMS / NEMS (C)

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